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# Heterojunction Bipolar Transistor Technology (InGaP HBT)

## High Efficiency/Linearity Amplifier

The MMZ25332B is a 2-stage, high linearity InGaP HBT broadband amplifier designed for femtocell, picocell, WLAN (802.11g/n), W-CDMA, TD-SCDMA and LTE wireless broadband applications. It provides exceptional linearity for LTE and W-CDMA air interfaces with an ACPR of -50 dBc at an output power of up to 22 dBm, covering frequencies from 1800–2800 MHz. It operates from a supply voltage of 3 to 5 volts. The amplifier is fully input matched, requires minimal external matching on the output and is housed in a cost-effective, surface mount QFN 3 × 3 package. The device offers state-of-the-art reliability, ruggedness, temperature stability and ESD performance.

- Typical Performance:  $V_{CC1} = V_{CC2} = V_{BIAS} = 5$  Volts,  $I_{CQ} = 400$  mA

Frequency	$P_{out}$ (dBm)	$G_{ps}$ (dB)	ACPR (dBc)	PAE (%)	Test Signal
2140 MHz	22	27.0	-50.0	7.0	W-CDMA
2620 MHz	21	26.0	-50.0	5.0	LTE 20 MHz

### Features

- Frequency: 1800–2800 MHz
- P1dB: 33 dBm @ 2500 MHz
- Power Gain: 26.5 dB @ 2500 MHz
- OIP3: 48 dBm @ 2500 MHz
- $EVM \leq 3\%$  @ 23.5 dBm  $P_{out}$ , WLAN (802.11g)
- Active Bias Control (adjustable externally)
- Power Down Control via  $V_{BIAS}$  Pin
- Class 3A HBM ESD Rating
- Single 3 to 5 Volt Supply
- Single-ended Power Detector
- Cost-effective QFN 3 × 3 Surface Mount Package
- In Tape and Reel. T1 Suffix = 1,000 Units, 12 mm Tape Width, 7-inch Reel.

**Table 1. Typical CW Performance (1)**

Characteristic	Symbol	1800 MHz	2500 MHz	2800 MHz	Unit
Small-Signal Gain (S21)	$G_p$	27.6	26.5	25.0	dB
Input Return Loss (S11)	IRL	-26	-17	-16	dB
Output Return Loss (S22)	ORL	-9	-17	-16	dB
Power Output @ 1dB Compression	P1dB	32	33	32	dBm

1.  $V_{CC1} = V_{CC2} = V_{BIAS} = 5$  Vdc,  $T_A = 25^\circ\text{C}$ , 50 ohm system, CW Application Circuit

**Table 2. Maximum Ratings**

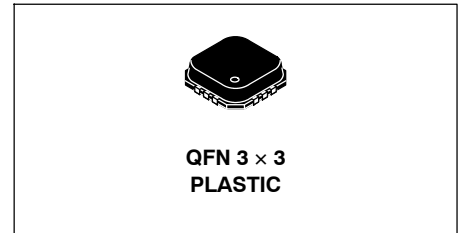
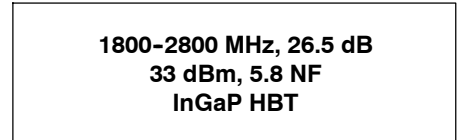
Rating	Symbol	Value	Unit
Supply Voltage	$V_{CC}$	6	V
Supply Current	$I_{CC}$	1200	mA
RF Input Power	$P_{in}$	30	dBm
Storage Temperature Range	$T_{stg}$	-65 to +150	$^\circ\text{C}$
Junction Temperature (2)	$T_J$	150	$^\circ\text{C}$

2. For reliable operation, the junction temperature should not exceed  $150^\circ\text{C}$ .

**Table 3. Thermal Characteristics**

Characteristic	Symbol	Value (3)	Unit
Thermal Resistance, Junction to Case Case Temperature $92^\circ\text{C}$ , $V_{CC1} = V_{CC2} = V_{BIAS} = 5$ Vdc	$R_{\theta JC}$	16	$^\circ\text{C}/\text{W}$

3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.



**Table 4. Electrical Characteristics<sup>(1)</sup>** ( $V_{CC1} = V_{CC2} = V_{BIAS} = 5 \text{ Vdc}$ , 2500 MHz,  $T_A = 25^\circ\text{C}$ , 50 ohm system, in Freescale CW Application Circuit)

Characteristic	Symbol	Min	Typ	Max	Unit
Small-Signal Gain (S21)	$G_p$	25	26.5	—	dB
Input Return Loss (S11)	IRL	—	-17	—	dB
Output Return Loss (S22)	ORL	—	-17	—	dB
Power Output @ 1dB Compression	P1dB	—	33	—	dBm
Third Order Output Intercept Point, Two-Tone CW	OIP3	—	48	—	dBm
Noise Figure	NF	—	5.8	—	dB
Supply Current <sup>(2)</sup>	$I_{CQ}$	356	390	412	mA
Supply Voltage <sup>(2)</sup>	$V_{CC}$	—	5	—	V

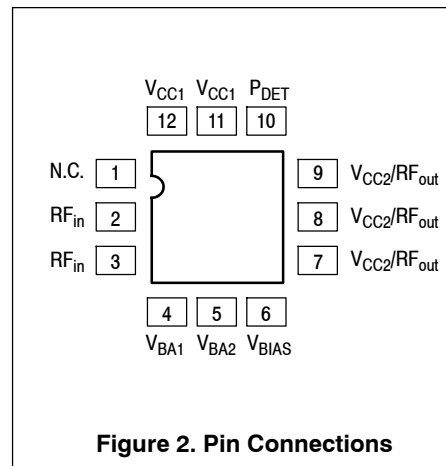
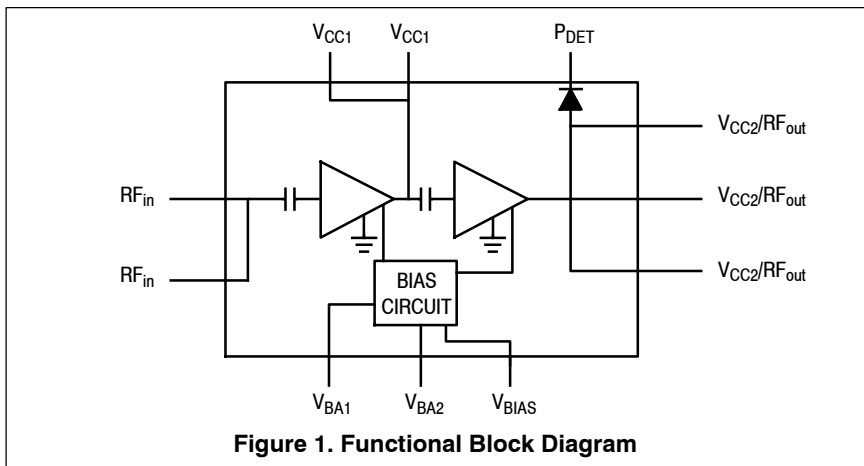
**Table 5. ESD Protection Characteristics**

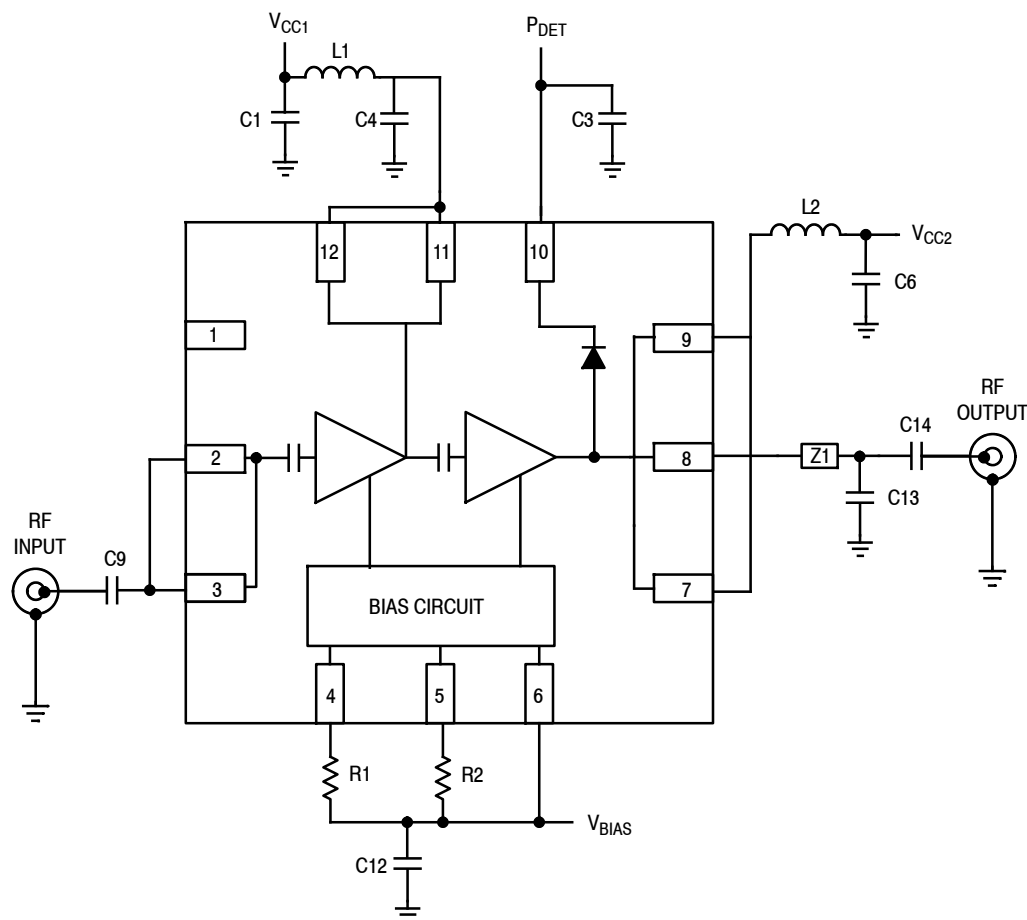
Test Methodology	Class
Human Body Model (per JESD22-A114)	3A
Machine Model (per EIA/JESD22-A115)	B
Charge Device Model (per JESD22-C101)	IV

**Table 6. Moisture Sensitivity Level**

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD22-A113, IPC/JEDEC J-STD-020	1	260	$^\circ\text{C}$

1. See Appendix A for test fixture documentation.
2. For reliable operation, the junction temperature should not exceed  $150^\circ\text{C}$ .





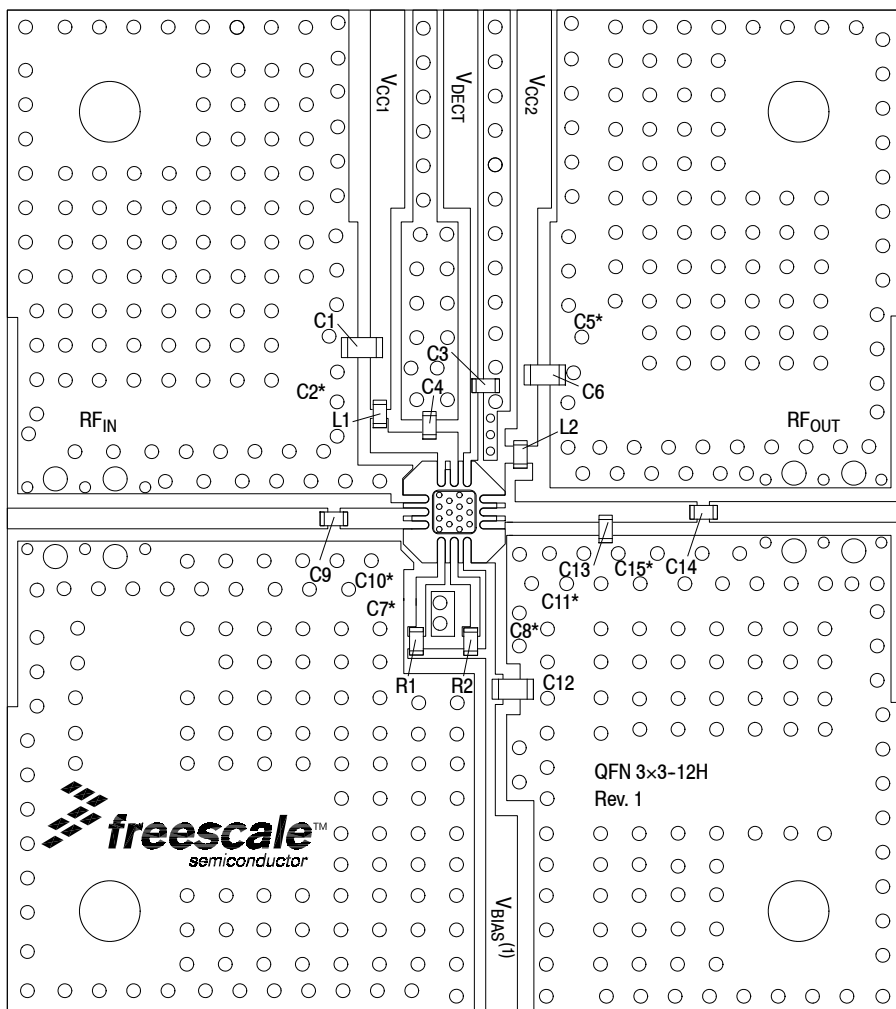
Z1 0.151" x 0.030" Microstrip

Figure 3. MMZ25332BT1 Test Circuit Schematic — 2140 MHz, 5 Volt Operation

Table 7. MMZ25332BT1 Test Circuit Component Designations and Values — 2140 MHz, 5 Volt Operation

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C7, C8, C10, C11, C15	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01	Murata
C4	8.2 pF Chip Capacitor	04023J8R2BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	3.3 pF Chip Capacitor	04023J3R3BBS	AVX
L1	12 nH Chip Inductor	0603HC-12NXJLW	Coilcraft
L2	6.8 nH Chip Inductor	0603HC-6N8XJLW	Coilcraft
R1	1.2 k $\Omega$ , 1/16 W Chip Resistor	RC0402JR-071K2L	Yageo
R2	330 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07330L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

Note: Component numbers C2, C5, C7, C8, C10, C11 and C15 are labeled on board but not placed.



(1)  $V_{BIAS}$  [Board] supplies  $V_{BA1}$ ,  $V_{BA2}$  and  $V_{BIAS}$  [Device].

Note: Component numbers C2\*, C5\*, C7\*, C8\*, C10\*, C11\* and C15\* are labeled on board but not placed.

**Figure 4. MMZ25332BT1 Test Circuit Component Layout — 2140 MHz, 5 Volt Operation**

**Table 7. MMZ25332BT1 Test Circuit Component Designations and Values — 2140 MHz, 5 Volt Operation**

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C7, C8, C10, C11, C15	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01	Murata
C4	8.2 pF Chip Capacitor	04023J8R2BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	3.3 pF Chip Capacitor	04023J3R3BBS	AVX
L1	12 nH Chip Inductor	0603HC-12NXJLW	Coilcraft
L2	6.8 nH Chip Inductor	0603HC-6N8XJLW	Coilcraft
R1	1.2 k $\Omega$ , 1/16 W Chip Resistor	RC0402JR-071K2L	Yageo
R2	330 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07330L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

(Test Circuit Component Designations and Values table repeated for reference.)

TYPICAL CHARACTERISTICS — 2140 MHz, 5 VOLT OPERATION

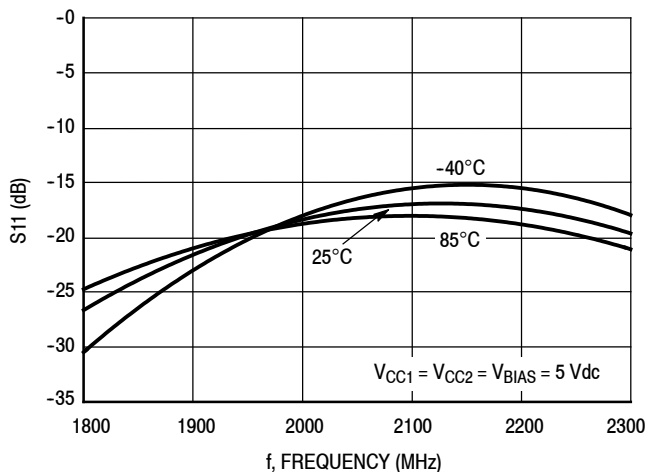


Figure 5. S11 versus Frequency versus Temperature

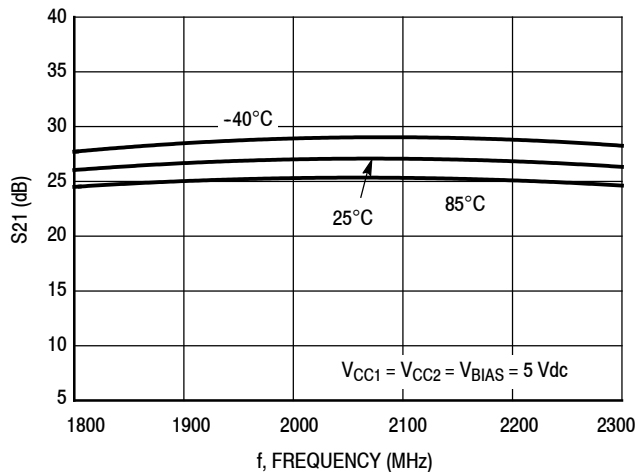


Figure 6. S21 versus Frequency versus Temperature

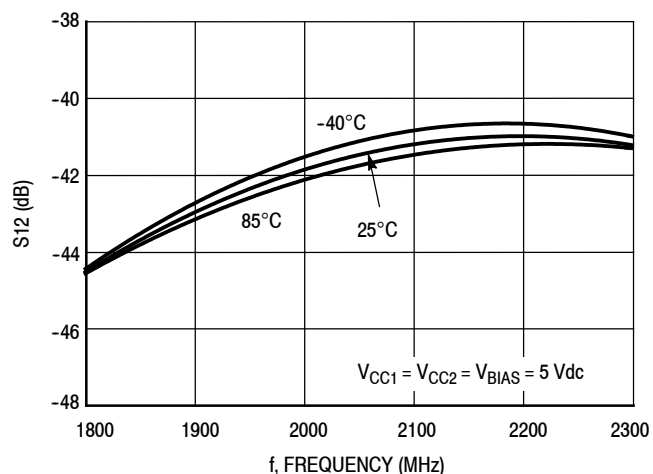


Figure 7. S12 versus Frequency versus Temperature

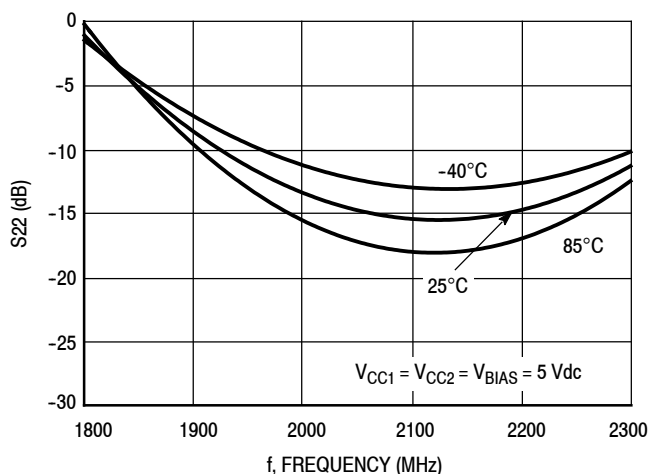


Figure 8. S22 versus Frequency versus Temperature

TYPICAL CHARACTERISTICS — 2140 MHz, 5 VOLT OPERATION

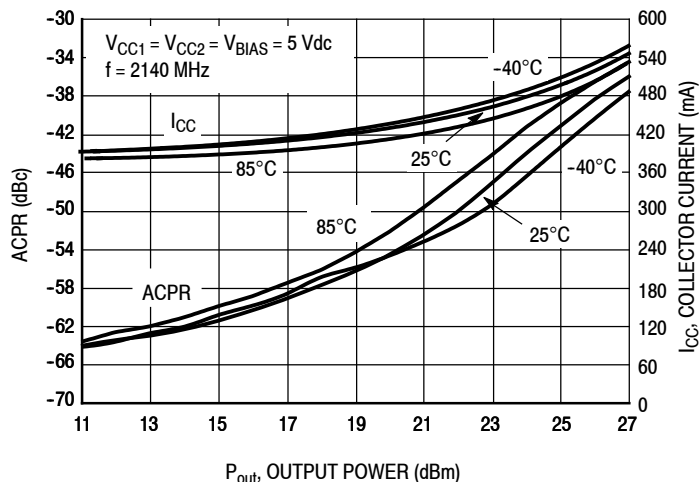


Figure 9. ACPR and Collector Current versus Output Power versus Temperature — 2140 MHz

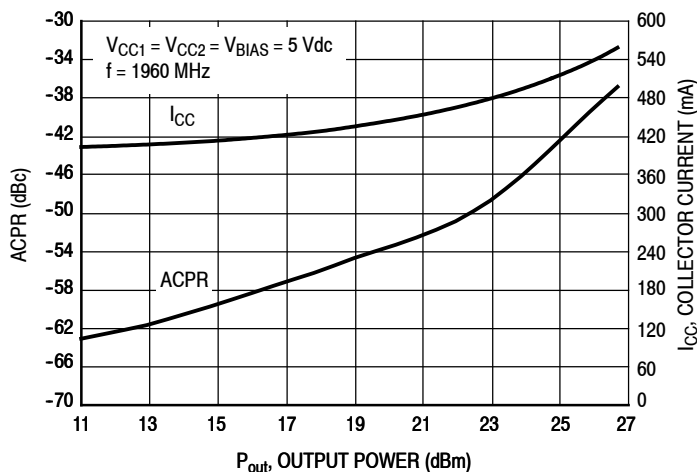


Figure 9a. ACPR and Collector Current versus Output Power — 1960 MHz

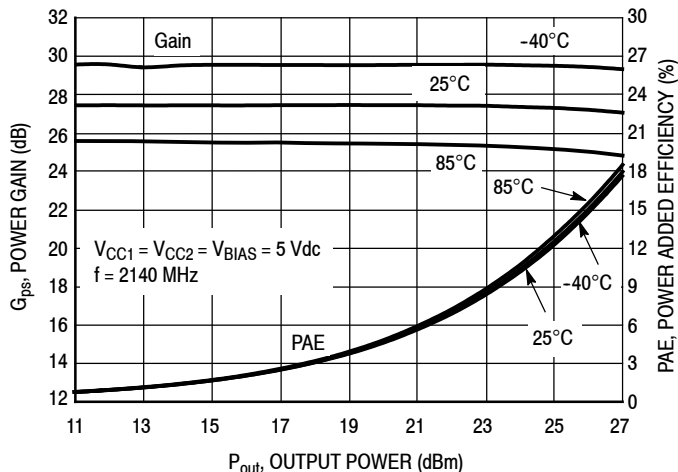


Figure 10. Power Gain and Power Added Efficiency versus Output Power versus Temperature

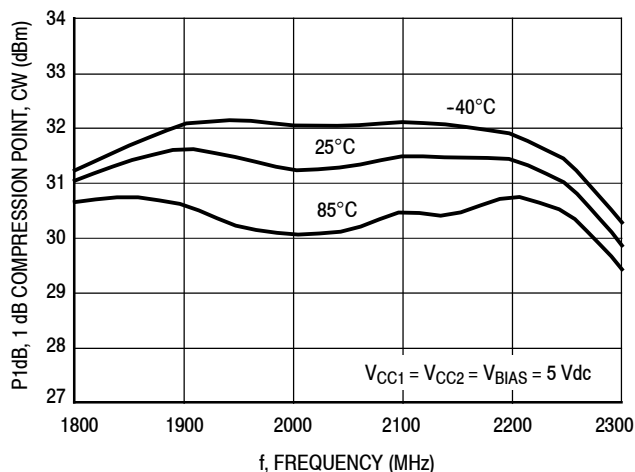


Figure 11. P1dB versus Frequency versus Temperature, CW

TYPICAL CHARACTERISTICS — 2140 MHz, 5 VOLT OPERATION

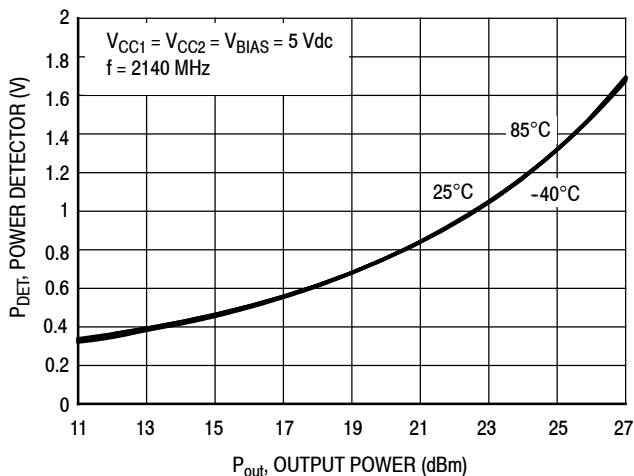
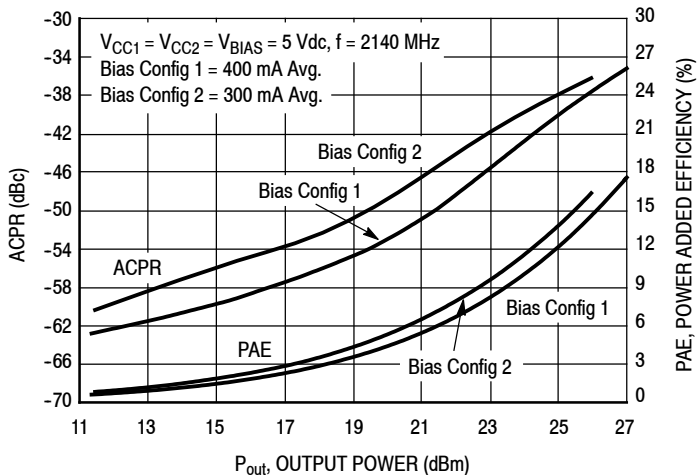
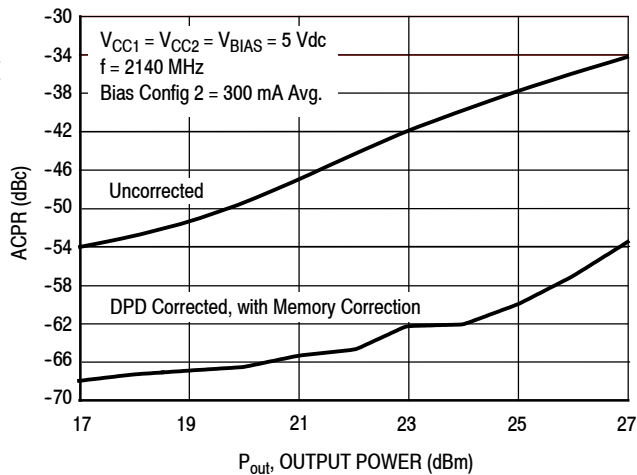


Figure 12. Power Detector versus Output Power versus Temperature



Note: Bias Config 1: 400 mA Avg. using R2 = 330 Ω  
Bias Config 2: 300 mA Avg. using R2 = 470 Ω

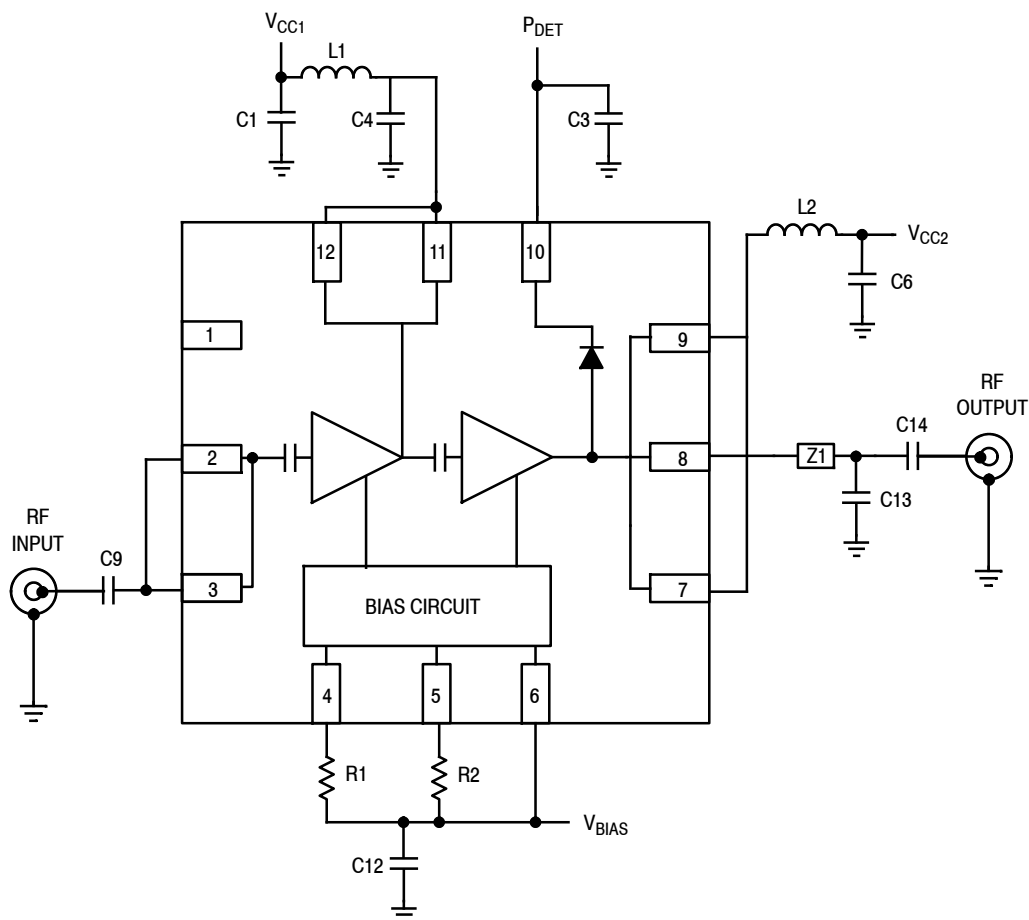
Figure 13. ACPR and Power Added Efficiency versus Output Power



Note: Bias Config 2: 300 mA Avg. using R2 = 470 Ω

Figure 14. ACPR versus Output Power with Bias Config 2 Uncorrected and Bias Config 2 DPD Corrected





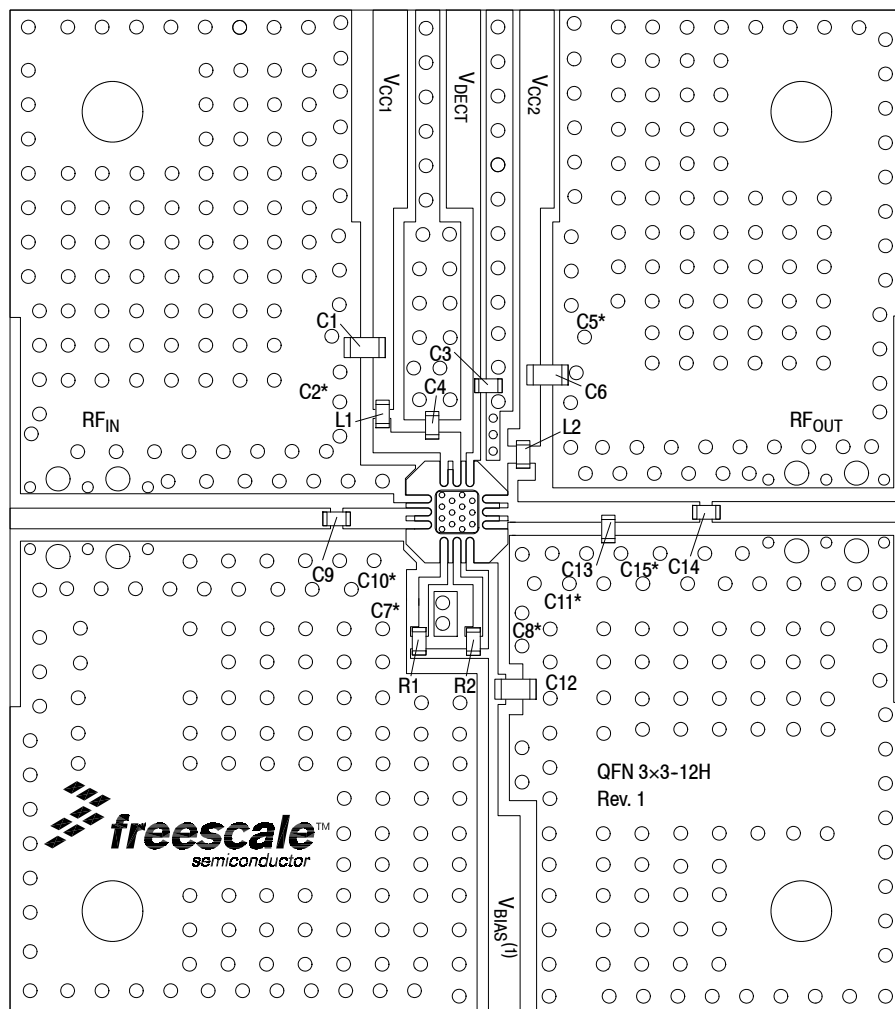
Z1 0.151" x 0.030" Microstrip

Figure 15. MMZ25332BT1 Test Circuit Schematic — 2140 MHz, 3.3 Volt Operation

Table 8. MMZ25332BT1 Test Circuit Component Designations and Values — 2140 MHz, 3.3 Volt Operation

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C7, C8, C10, C11, C15	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01	Murata
C4	8.2 pF Chip Capacitor	04023J8R2BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	3.3 pF Chip Capacitor	04023J3R3BBS	AVX
L1	12 nH Chip Inductor	0603HC-12NXJLW	Coilcraft
L2	6.8 nH Chip Inductor	0603HC-6N8XJLW	Coilcraft
R1	500 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07500L	Yageo
R2	90 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-0790L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

Note: Component numbers C2, C5, C7, C8, C10, C11 and C15 are labeled on board but not placed.



(1) V<sub>BIAS</sub> [Board] supplies V<sub>BA1</sub>, V<sub>BA2</sub> and V<sub>BIAS</sub> [Device].

Note: Component numbers C2\*, C5\*, C7\*, C8\*, C10\*, C11\* and C15\* are labeled on board but not placed.

**Figure 16. MMZ25332BT1 Test Circuit Component Layout — 2140 MHz, 3.3 Volt Operation**

**Table 8. MMZ25332BT1 Test Circuit Component Designations and Values — 2140 MHz, 3.3 Volt Operation**

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C7, C8, C10, C11, C15	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01	Murata
C4	8.2 pF Chip Capacitor	04023J8R2BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	3.3 pF Chip Capacitor	04023J3R3BBS	AVX
L1	12 nH Chip Inductor	0603HC-12NXJLW	Coilcraft
L2	6.8 nH Chip Inductor	0603HC-6N8XJLW	Coilcraft
R1	500 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07500L	Yageo
R2	90 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-0790L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

(Test Circuit Component Designations and Values table repeated for reference.)

TYPICAL CHARACTERISTICS — 2140 MHz, 3.3 VOLT OPERATION

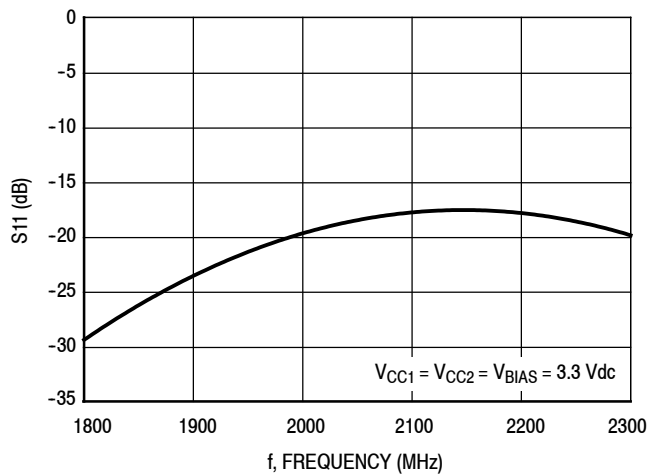


Figure 17. S11 versus Frequency

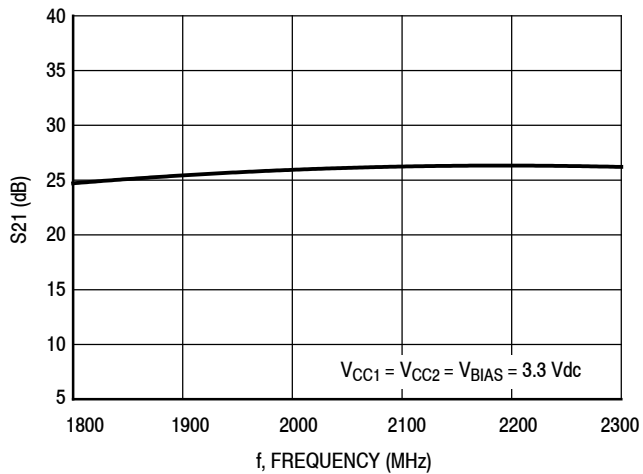


Figure 18. S21 versus Frequency

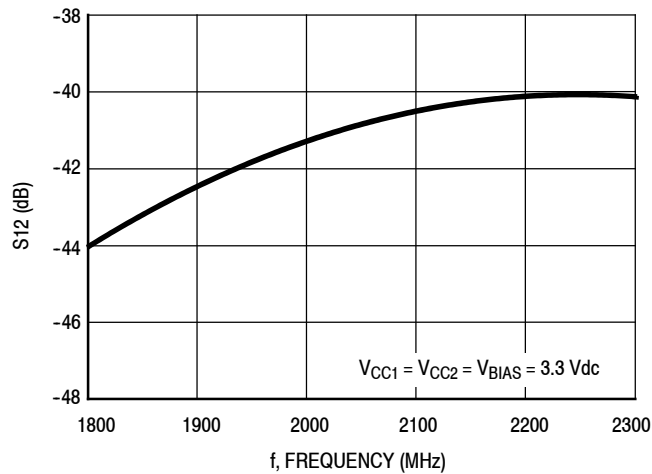


Figure 19. S12 versus Frequency

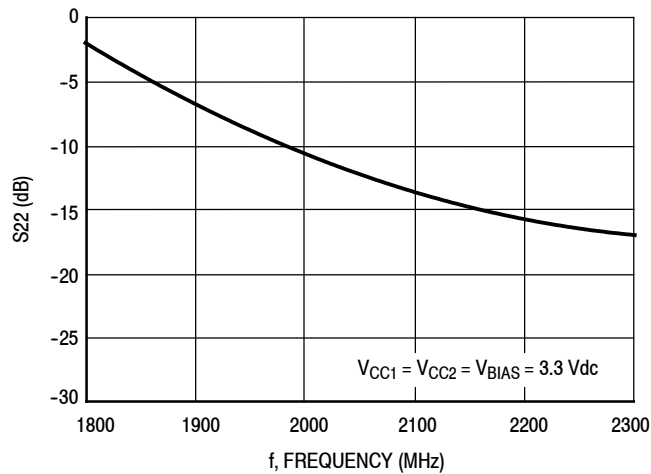


Figure 20. S22 versus Frequency

TYPICAL CHARACTERISTICS — 2140 MHz, 3.3 VOLT OPERATION

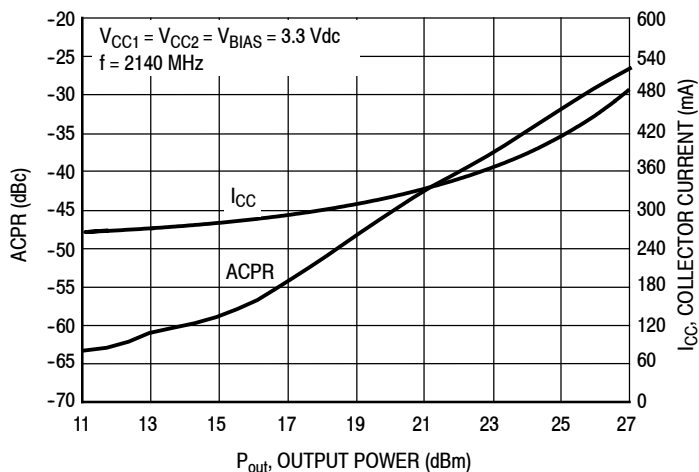


Figure 21. ACPR and Collector Current versus Output Power

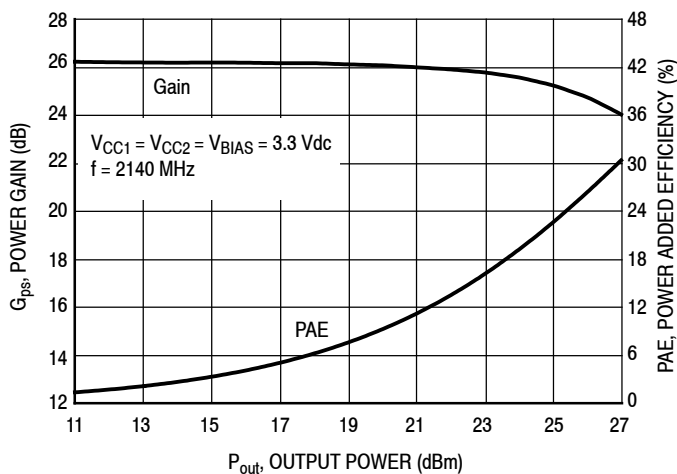


Figure 22. Power Gain and Power Added Efficiency versus Output Power

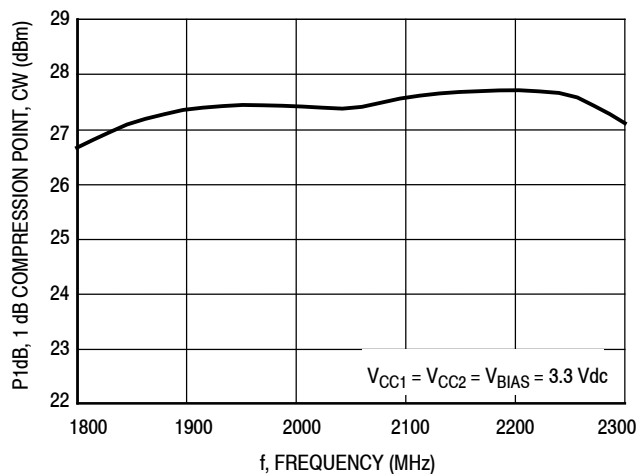


Figure 23. P1dB versus Frequency, CW

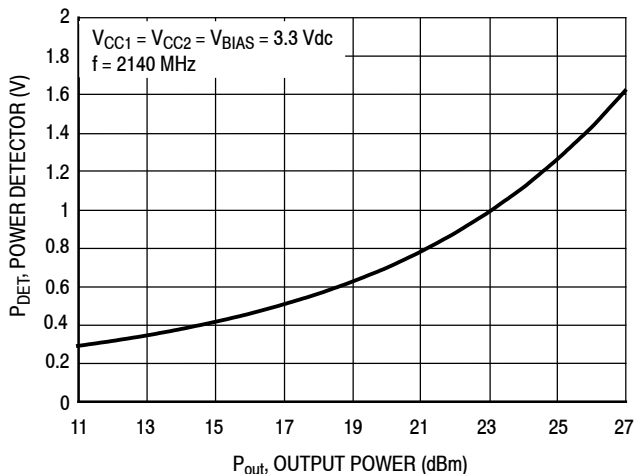


Figure 24. Power Detector versus Output Power

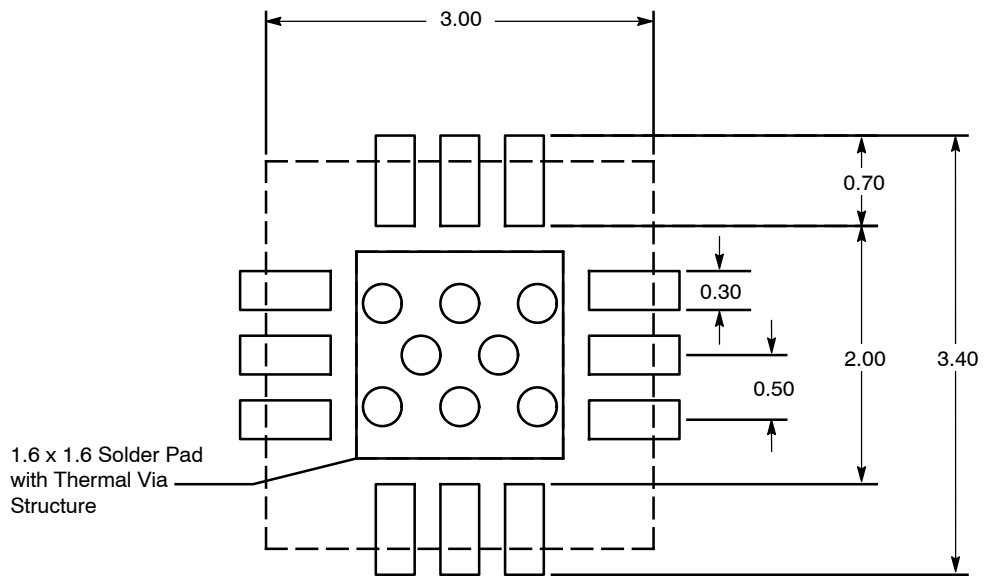


Figure 25. PCB Pad Layout for QFN 3 × 3

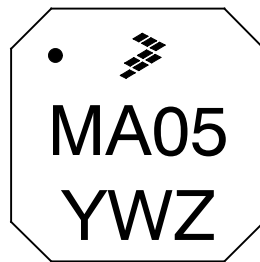
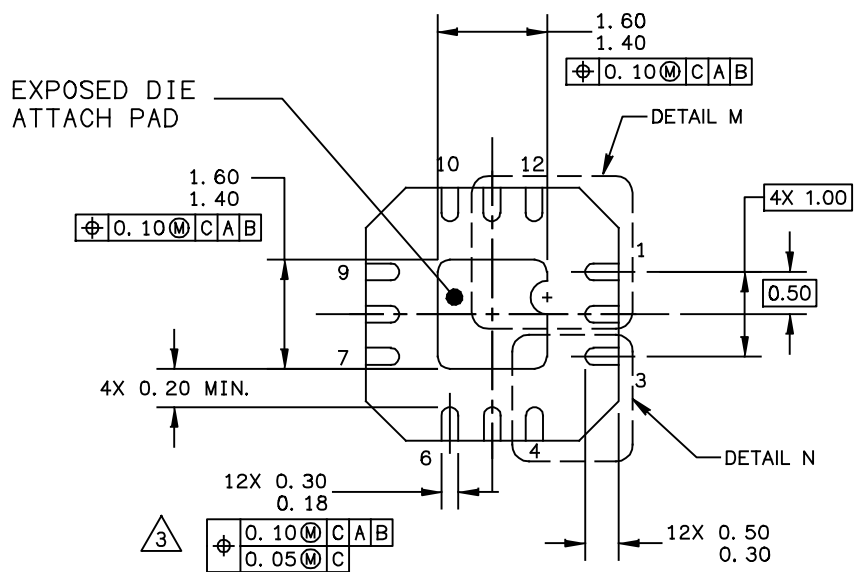
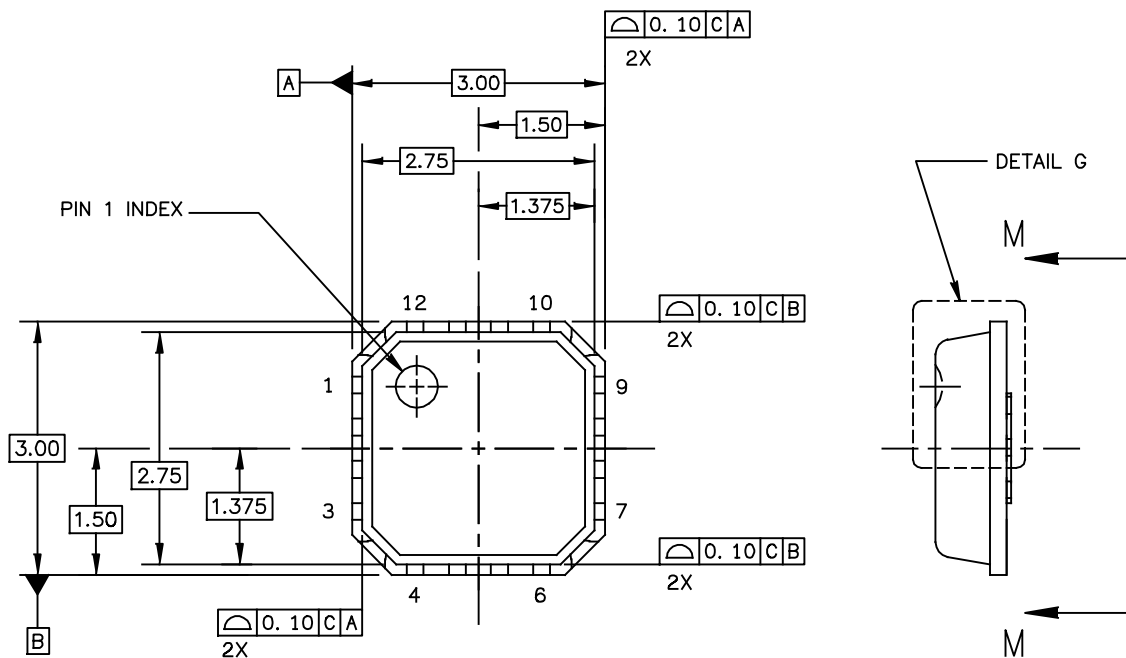


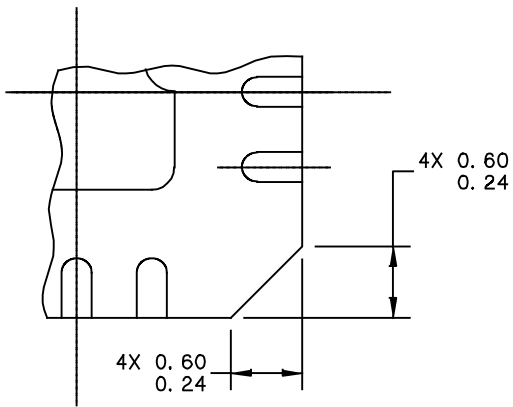
Figure 26. Product Marking

PACKAGE DIMENSIONS

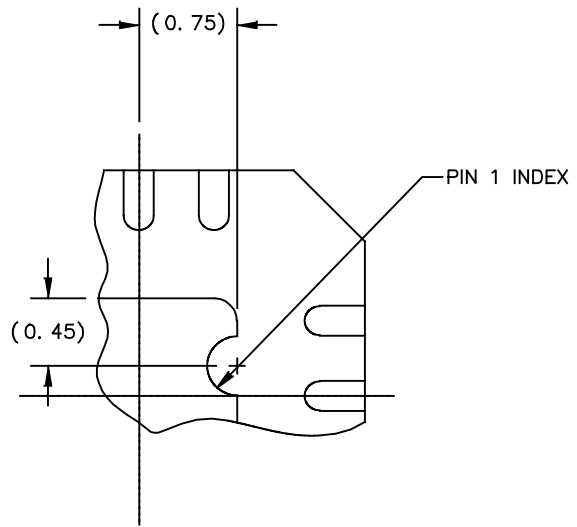


VIEW M-M

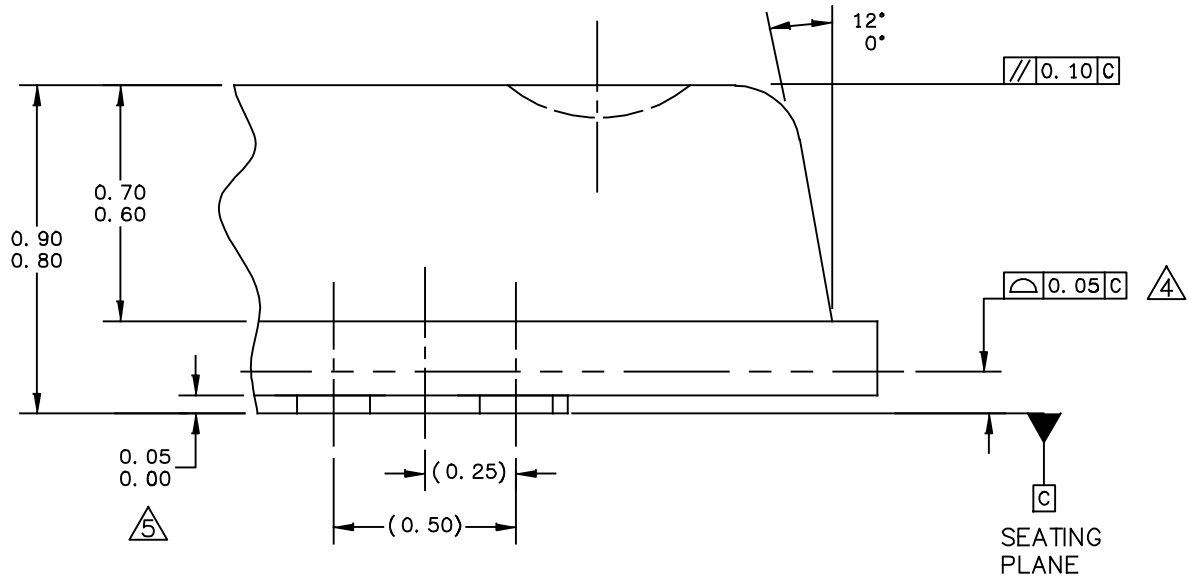
<p>© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.</p>	<p>MECHANICAL OUTLINE</p>	<p>PRINT VERSION NOT TO SCALE</p>	
<p>TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 12 TERMINAL, 0.5 PITCH (3X3X0.85)</p>		<p>DOCUMENT NO: 98ASA00227D</p>	<p>REV: 0</p>
		<p>CASE NUMBER: 2131-01</p>	<p>14 MAY 2010</p>
		<p>STANDARD: NON-JEDEC</p>	



DETAIL N  
CORNER CONFIGURATION



DETAIL M  
PIN 1 BACKSIDE INDEX



DETAIL G  
VIEW ROTATED 90° CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 12 TERMINAL, 0.5 PITCH (3X3X0.85)	DOCUMENT NO: 98ASA00227D	REV: 0	
	CASE NUMBER: 2131-01	14 MAY 2010	
	STANDARD: NON-JEDEC		

NOTE:

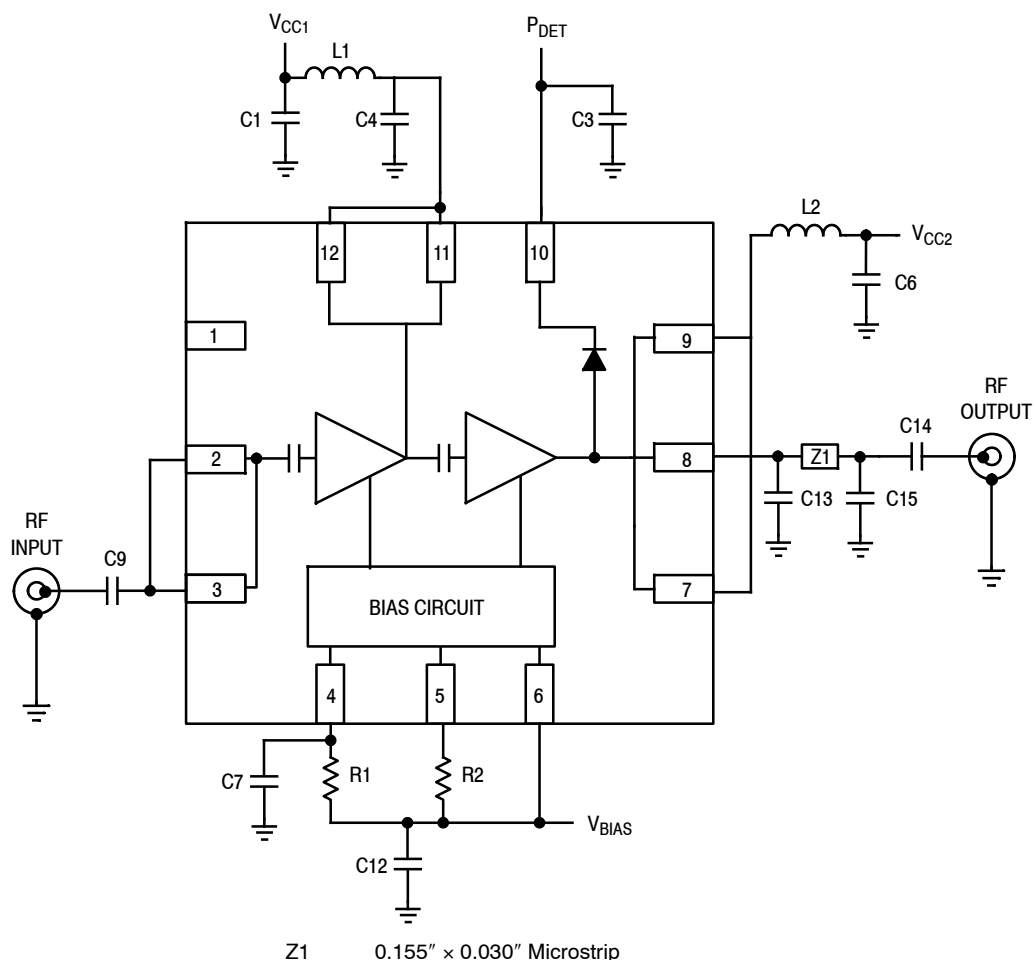
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING & TOLERANCING PER ASME Y14.5 – 2009.
3. THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DIMENSION APPLIED ONLY FOR TERMINALS.

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 12 TERMINAL, 0.5 PITCH (3X3X0.85)		DOCUMENT NO: 98ASA00227D	REV: 0
		CASE NUMBER: 2131-01	14 MAY 2010
		STANDARD: NON-JEDEC	



## APPENDIX A

### MMZ25332BT1 TEST CIRCUIT SCHEMATIC, FIXTURE AND PARTS LIST

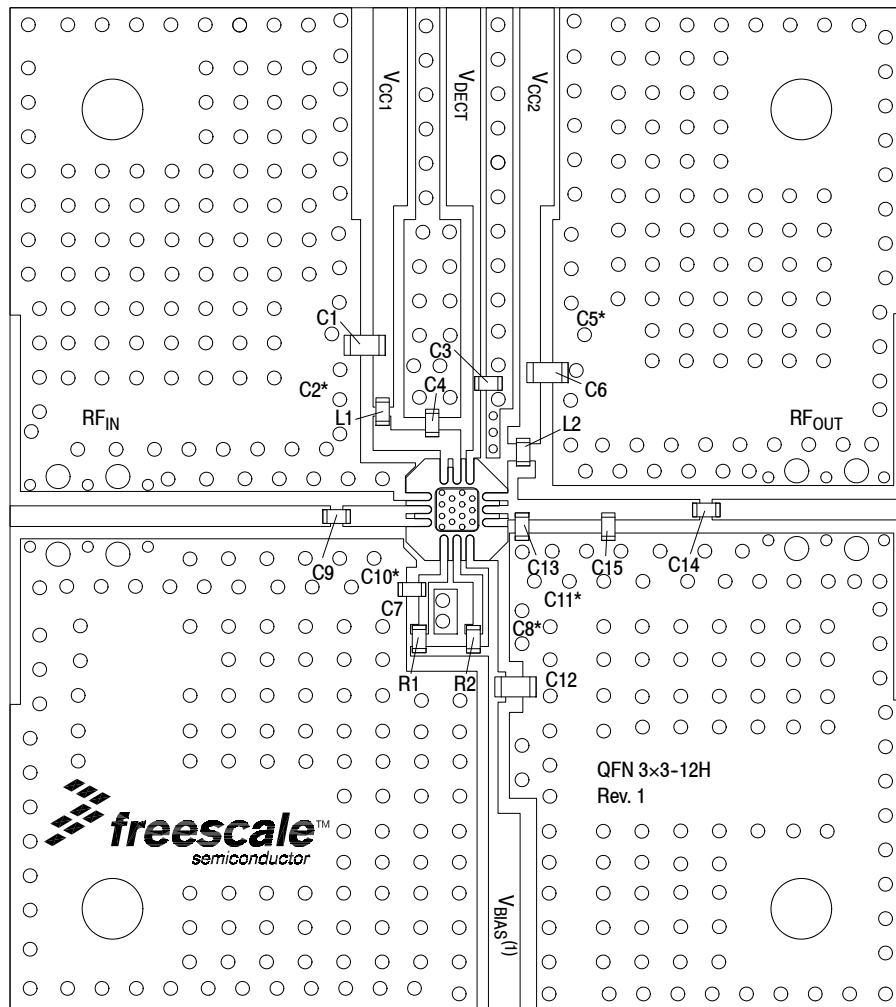


**Figure 27. MMZ25332BT1 Test Circuit Schematic — 2500 MHz, 5 Volt Operation**

**Table 9. MMZ25332BT1 Test Circuit Component Designations and Values — 2500 MHz, 5 Volt Operation**

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C8, C10, C11	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01D	Murata
C4	7.5 pF Chip Capacitor	04023J7R5BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C7	120 pF Chip Capacitor	GRM1555C1H121JA01D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	2.4 pF Chip Capacitor	04023J2R4BBS	AVX
C15	1.8 pF Chip Capacitor	04023J1R8BBS	AVX
L1	24 nH Chip Inductor	0603HC-24NXJLW	Coilcraft
L2	22 nH Chip Inductor	0603HC-22NXJLW	Coilcraft
R1	1.2 k $\Omega$ , 1/16 W Chip Resistor	RC0402JR-071K2L	Yageo
R2	330 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07330L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

Note: Component numbers C2, C5, C8, C10 and C11 are labeled on board but not placed.



(1) VBIAS [Board] supplies V<sub>BA1</sub>, V<sub>BA2</sub> and V<sub>BIAS</sub> [Device].  
 Note: Component numbers C2\*, C5\*, C8\*, C10\* and C11\* are labeled on board but not placed.

**Figure 28. MMZ25332BT1 Test Circuit Component Layout — 2500 MHz, 5 Volt Operation**

**Table 9. MMZ25332BT1 Test Circuit Component Designations and Values — 2500 MHz, 5 Volt Operation**

Part	Description	Part Number	Manufacturer
C1, C12	1 $\mu$ F Chip Capacitors	GRM155R61A105KE15	Murata
C2, C5, C8, C10, C11	Components Not Placed		
C3	470 pF Chip Capacitor	GRM1555C1H471JA01D	Murata
C4	7.5 pF Chip Capacitor	04023J7R5BBS	AVX
C6	4.7 $\mu$ F Chip Capacitor	GRM188R60J475KE19D	Murata
C7	120 pF Chip Capacitor	GRM1555C1H121JA01D	Murata
C9, C14	22 pF Chip Capacitors	04023J22R0BBS	AVX
C13	2.4 pF Chip Capacitor	04023J2R4BBS	AVX
C15	1.8 pF Chip Capacitor	04023J1R8BBS	AVX
L1	24 nH Chip Inductor	0603HC-24NXJLW	Coilcraft
L2	22 nH Chip Inductor	0603HC-22NXJLW	Coilcraft
R1	1.2 k $\Omega$ , 1/16 W Chip Resistor	RC0402JR-071K2L	Yageo
R2	330 $\Omega$ , 1/16 W Chip Resistor	RC0402JR-07330L	Yageo
PCB	0.014", $\epsilon_r = 3.7$	FR408	Isola

(Test Circuit Component Designations and Values table repeated for reference.)

## PRODUCT DOCUMENTATION, SOFTWARE AND TOOLS

Refer to the following documents, software and tools to aid your design process.

### Application Notes

- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

### Software

- .s2p File

### Development Tools

- Printed Circuit Boards

For Software and Tools, do a Part Number search at <http://www.freescale.com>, and select the “Part Number” link. Go to the Software & Tools tab on the part’s Product Summary page to download the respective tool.

## REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	May 2012	<ul style="list-style-type: none"><li>• Initial Release of Data Sheet</li></ul>
1	Dec. 2012	<ul style="list-style-type: none"><li>• Added 2140 MHz, 5 Volt Operation, as follows:<ul style="list-style-type: none"><li>- Fig. 3, Test Circuit Schematic, p. 3</li><li>- Table 7, Test Circuit Component Designations and Values, p. 3</li><li>- Fig. 4, Test Circuit Component Layout, p. 4</li><li>- Fig. 5, S11 versus Frequency versus Temperature, p. 5</li><li>- Fig. 6, S21 versus Frequency versus Temperature, p. 5</li><li>- Fig. 7, S12 versus Frequency versus Temperature, p. 5</li><li>- Fig. 8, S22 versus Frequency versus Temperature, p. 5</li><li>- Fig. 9, ACPR and Collector Current versus Output Power versus Temperature — 2140 MHz, p.6</li><li>- Fig. 9a, ACPR and Collector Current versus Output Power — 1960 MHz, p.6</li><li>- Fig. 10, Power Gain and Power Added Efficiency versus Output Power versus Temperature, p. 6</li><li>- Fig. 11, P1dB versus Frequency versus Temperature, CW, p. 6</li><li>- Fig. 12, Power Detector versus Output Power versus Temperature, p. 7</li><li>- Fig. 13, ACPR and Power Added Efficiency versus Output Power, p. 7</li><li>- Fig. 14, ACPR versus Output Power with Bias Config 2 Uncorrected and Bias Config 2 DPD Corrected, p. 7</li></ul></li><li>• Added 2140 MHz, 3.3 Volt Operation, as follows:<ul style="list-style-type: none"><li>- Fig. 15, Test Circuit Schematic, p. 8</li><li>- Table 8, Test Circuit Component Designations and Values, p. 8</li><li>- Fig. 16, Test Circuit Component Layout, p. 9</li><li>- Fig. 17, S11 versus Frequency versus Temperature, p. 10</li><li>- Fig. 18, S21 versus Frequency versus Temperature, p. 10</li><li>- Fig. 19, S12 versus Frequency versus Temperature, p. 10</li><li>- Fig. 20, S22 versus Frequency versus Temperature, p. 10</li><li>- Fig. 21, ACPR and Collector Current versus Output Power, p. 11</li><li>- Fig. 22, Power Gain and Power Added Efficiency versus Output Power, p. 11</li><li>- Fig. 23, P1dB versus Frequency, CW, p. 11</li><li>- Fig. 24, Power Detector versus Output Power, p. 11</li></ul></li><li>• Added Appendix A, Test Circuit Schematic, Fixture and Parts List (for 2500 MHz, 5 Volt Operation) as follows:<ul style="list-style-type: none"><li>- Moved former Fig. 3 (now Fig. 27), Test Circuit Schematic, to p. 16</li><li>- Moved former Table 7 (now Table 9), Test Circuit Component Designations and Values, to p.16</li><li>- Moved former Fig. 4 (now Fig. 28), Test Circuit Component Layout, to p.17</li></ul></li></ul>

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